

2SJ505(L), 2SJ505(S)

Silicon P Channel MOS FET

REJ03G0872-0500 Rev.5.00 Jun 05, 2006

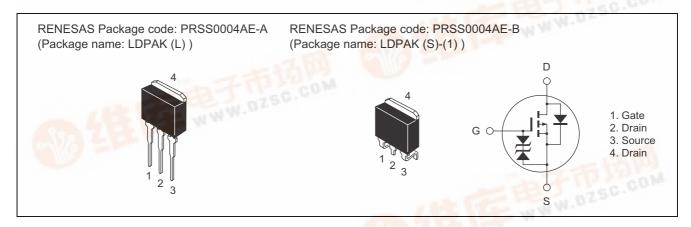
Description

High speed power switching

Features

- Low on-resistance $R_{DS \text{ (on)}} = 0.017 \Omega \text{ typ.}$
- Low drive current.
- 4 V gate drive devices.
- High speed switching.

Outline





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	-50	Α
Drain peak current	I _{D (pulse)} Note 1	-200	A
Body to drain diode reverse drain current	I _{DR}	-50	Α
Avalanche current	I _{AP} Note 3	-50	Α
Avalanche energy	E _{AR} Note 3	214	mJ
Channel dissipation	Pch Note 2	75	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $Tc = 25^{\circ}C$

3. Value at Ta = 25°C, Rg \geq 50 Ω

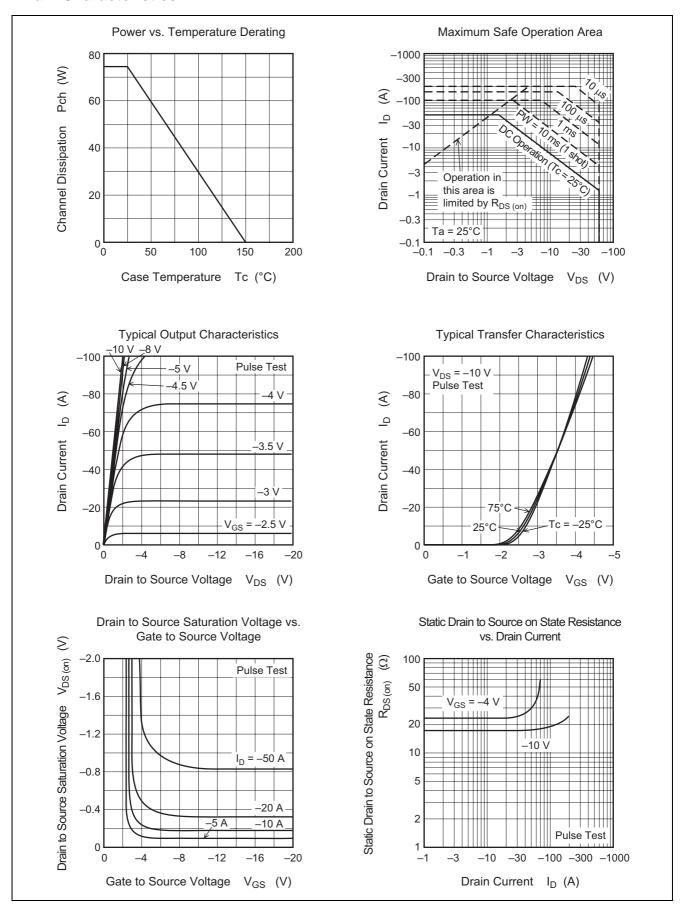
Electrical Characteristics

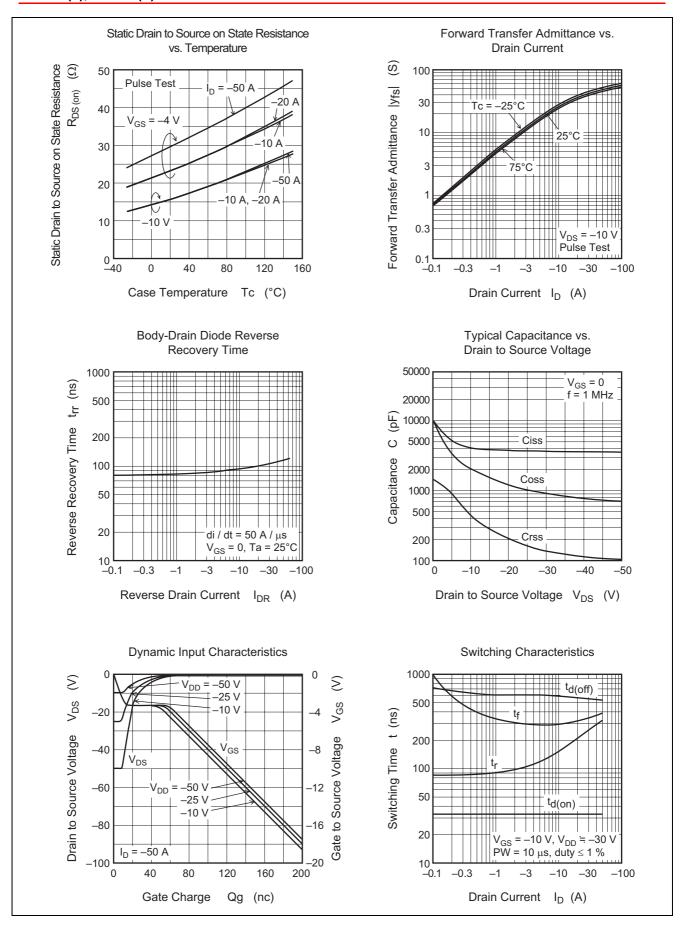
 $(Ta = 25^{\circ}C)$

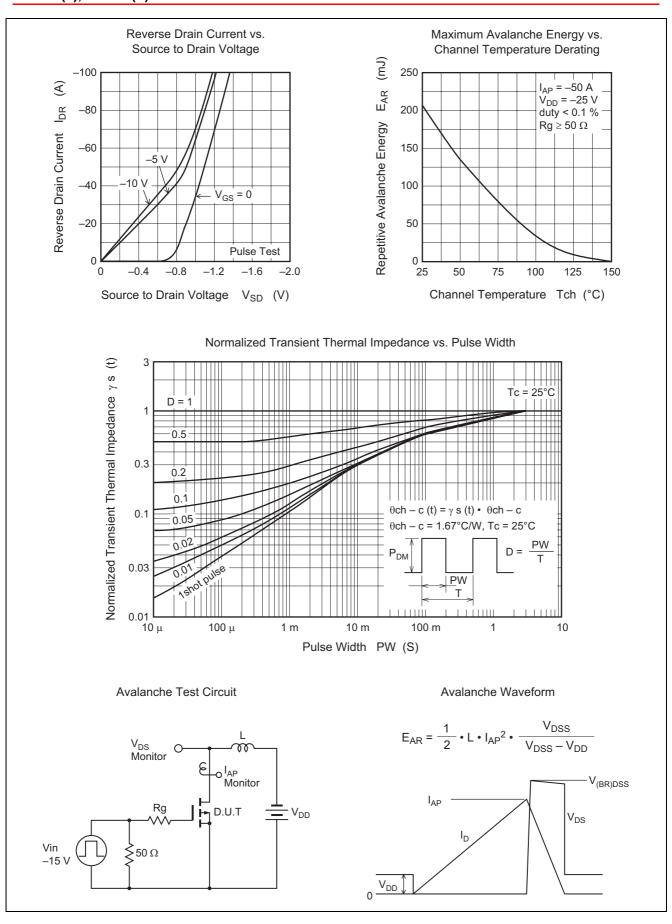
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	-60	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-10	μΑ	$V_{DS} = -60 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	_	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	_	0.017	0.022	Ω	$I_D = -25 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	0.024	0.036	Ω	$I_D = -25 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	27	39	_	S	$I_D = 25 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	4100	_	рF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	2100	_	рF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	450	_	рF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	32	_	ns	V _{GS} = -10 V
Rise time	t _r	_	225	_	ns	I _D = -25 A
Turn-off delay time	t _{d (off)}	_	530	_	ns	$R_L = 1.2 \Omega$
Fall time	t _f	_	330	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-1.1	_	V	$I_F = -50 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	110	_	ns	$I_F = -50 \text{ A}, V_{GS} = 0$
						$di_F/dt = 50 A/\mu s$

Note: 4. Pulse test

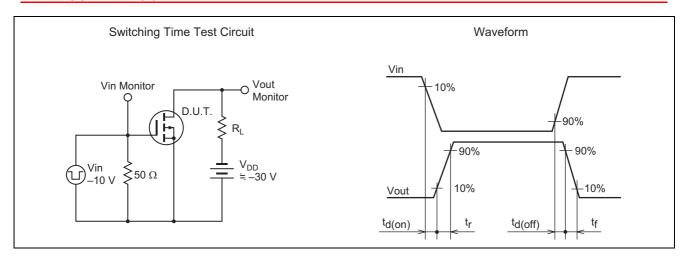
Main Characteristics



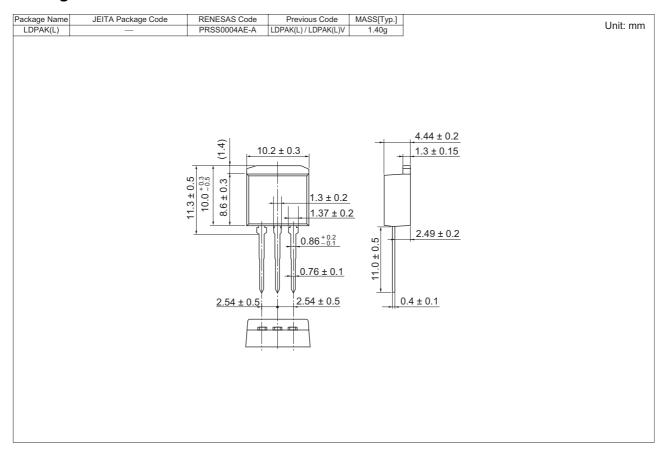


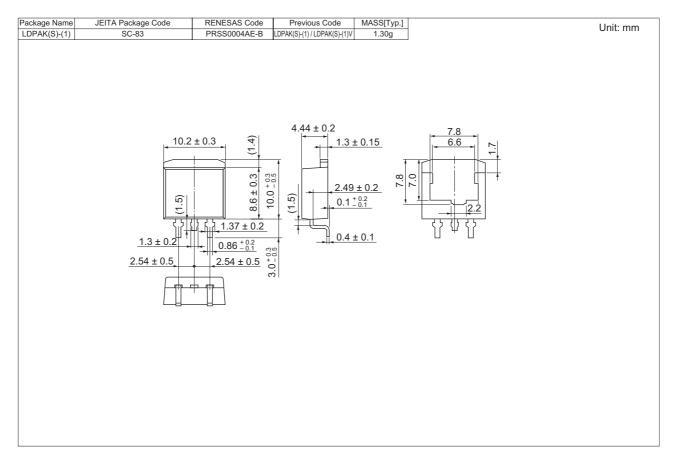


2SJ505(L), 2SJ505(S)



Package Dimensions





2SJ505(L), 2SJ505(S)

Ordering Information

Part Name	Quantity	Shipping Container
2SJ505L-E	500 pcs	Box (Sack)
2SJ505STL-E	1000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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